

IN THE CLAIMS:

Cancel claim 10, amend claims 1-9 and add claims 11-15 as follows:

CLAIMS

Claims

1. (Currently Amended) A carrier device (1) for a monolithic integrated circuit comprising:
~~(7), the carrier device (1) having~~ portions for the connection of bonding wires ~~(5, 6)~~ in the form of raised pedestals ~~(2, 2')~~ which rise above a chip connection area on the carrier device ~~(1)~~.

2. (Currently Amended) The A-carrier device (1) ~~as claimed in of~~ claim 1, wherein
~~characterized in that~~ the raised pedestals ~~(2, 2')~~ have sides (3) with an angle (α) greater than 45 degrees with respect to a ~~the~~ plane of the carrier device ~~(1)~~.

3. (Currently Amended) The A-carrier device (1) ~~of as claimed in~~ claim 1 ~~or~~ 2, wherein
~~characterized in that~~ the raised pedestals ~~(2, 2')~~ each have a plane surface which is parallel to a
~~the~~ plane of the chip connection area and each has an ~~comprises at least the~~ area for the connection of a single bonding wire ~~(5, 6)~~.

4. (Currently Amended) The A-carrier device (1) ~~as claimed in any one of~~ of claims 1 ~~to~~ 3,
wherein ~~characterized in that~~ a height (h_p) of each of the raised pedestals ~~(2, 2')~~ lies in the range between 1/10 and 1.5 times a ~~the~~ chip height.

5. (Currently Amended) The A carrier device (1) ~~as claimed in any one of~~ of claims 1 ~~to~~ 3,
wherein ~~characterized in that~~ a height (h_p) of each of the raised pedestals ~~(2, 2')~~ lies in the range from 1/5 to twice a ~~the~~ material thickness (h) of the carrier device ~~(1)~~.

6. (Currently Amended) ~~The A carrier device (1) of as claimed in any one of claims 1 to 5,~~
~~wherein characterized in that~~ the raised pedestals (2, 2') each represent a local deformation of the
 carrier device (1) which is formed by means of a punch or a bending-off device.

7. (Currently Amended) ~~The A carrier device (1) as claimed in any one of of claims 1 to 5,~~
~~wherein characterized in that~~ the raised pedestals (2, 2') are formed by application of material to
 the carrier device (1).

8. (Currently Amended) ~~The A carrier device (1) as claimed in any one of of claims 1 to 7,~~
~~wherein characterized in that only in the areas of the raised pedestals, a finish, particularly silver~~
 or gold, finish is applied to the raised pedestals ~~provided for bondability.~~

9. (Currently Amended) ~~The A carrier device (1) as claimed in any one of claims 1 to 8,~~
~~wherein characterized in that~~ there is at least one unbonded raised pedestal (2') on the carrier
 device (1).

10. (Cancelled)

11. (New) A carrier device for a monolithic integrated circuit, comprising:

a plurality of pedestals located on a common surface of an integrated circuit carrier
 device and raised in relief from the common surface, where in comparison to the area of the
 common surface, the respective areas of the raised pedestals are relatively small, so that a
 plurality of raised pedestals are produced on the carrier device by a punch-type tool pressing the

raised pedestals out of the carrier device in the manner of a stamping operation which does not penetrate the full carrier height.

12. (New) The carrier device of claim 11, where the raised pedestals serve bonding purposes and/or form fixed points in relation to a delamination.

13. (New) The carrier device of claim 11, where the raised pedestals make an angle (α) greater than 45 degrees with the plane of the carrier device at all sides, with the sides having rounded junctions parallel to the plane of the carrier device or being rounded as a whole.

14. (New) The carrier device of claim 11, where the height of the raised pedestals lies in the range between 1/10 of the chip height and the chip height itself.

15. (New) The carrier device of claim 11, where only in the areas of the raised pedestals, a finish, particularly silver or gold, is provided for bondability.